

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/03/2022

Details for "LP3982ILD-3.0/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LP3982ILD-3.0/NOPB	SN	Level-3-260C-168 HR	Texas Instruments Electronics	NGM 8	3 x 2.5 x 0.8	14.7

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.050539	98.734054	987341	0.344345	3443
Not Categorized	Proprietary Materials		0.000006	0.011722	117	0.000041	0
Precious Metals	Gold	7440-57-5	0.000011	0.02149	215	0.000075	1
Precious Metals	Palladium	7440-05-3	0.00063	1.230781	12308	0.004292	43
Precious Metals	Silver	7440-22-4	0.000001	0.001954	20	0.000007	0
Sub-Total			0.051187	100	1000000	0.34876	3488
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.173613	75	750000	1.182902	11829
Thermoplastics	Epoxy	85954-11-6	0.057871	25	250000	0.394301	3943
Sub-Total			0.231484	100	1000000	1.577203	15772
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	4.784585	95.729992	957300	32.599489	325995
Copper and Its Alloys	Iron	7439-89-6	0.117953	2.360004	23600	0.803666	8037
Copper and Its Alloys	Phosphorus	7723-14-0	0.001499	0.029992	300	0.010213	102
Precious Metals	Silver	7440-22-4	0.087965	1.760004	17600	0.599344	5993
Zinc and Its Alloys	Zinc	7440-66-6	0.005998	0.120008	1200	0.040867	409
Sub-Total			4.998	100	1000000	34.05358	340536
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.311	100	1000000	2.11898	21190
Sub-Total			0.311	100	1000000	2.11898	21190
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	7.69541	90.500005	905000	52.432225	524322
Thermoplastics	Epoxy	85954-11-6	0.807805	9.499995	95000	5.503932	55039
Sub-Total			8.503215	100	1000000	57.936157	579362
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.581985	100	1000000	3.965321	39653
Sub-Total			0.581985	100	1000000	3.965321	39653
Total			14.676871			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.